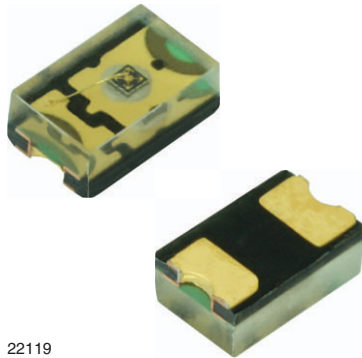


## High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology



22119

### DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY1850X01 is an infrared, 850 nm emitting diode based on GaAlAs surface emitter chip technology with high radiant intensity, high optical power and high speed, molded in clear, untinted 0805 plastic package for surface mounting (SMD).

### FEATURES

- Package type: surface mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- AEC-Q101 qualified
- Peak wavelength:  $\lambda_p = 850$  Nm
- High reliability
- High radiant power
- High radiant intensity
- High speed
- Angle of half sensitivity:  $\vartheta = \pm 60^\circ$
- Suitable for high pulse current operation
- 0805 standard surface-mountable package
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

 AUTOMOTIVE  
GRADE

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
**GREEN**  
(5-2008)

### APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR touch panels
- IR flash
- IR illumination
- 3D TV

PRODUCT SUMMARY				
COMPONENT	$I_e$ (mW/sr)	$\varphi$ (deg)	$\lambda_p$ (nm)	$t_r$ (ns)
VSMY1850X01	10	$\pm 60$	850	10

#### Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY1850X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

#### Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
Forward current		$I_F$	100	mA
Peak forward current	$t_p/T = 0.1, t_p = 100\text{ }\mu\text{s}$	$I_{FM}$	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	$I_{FSM}$	1	A
Power dissipation		$P_V$	190	mW
Junction temperature		$T_j$	100	$^{\circ}\text{C}$
Operating temperature range		$T_{amb}$	-40 to +85	$^{\circ}\text{C}$
Storage temperature range		$T_{stg}$	-40 to +100	$^{\circ}\text{C}$
Soldering temperature	acc. figure 7, J-STD-020	$T_{sd}$	260	$^{\circ}\text{C}$
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	$R_{thJA}$	270	K/W



Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

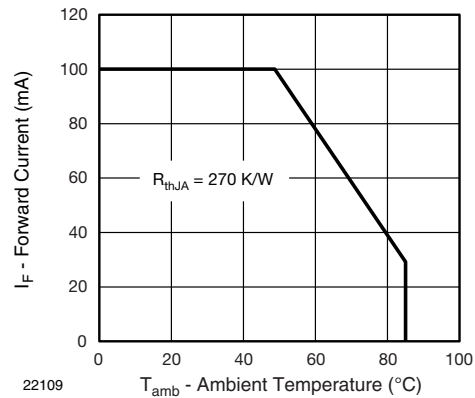
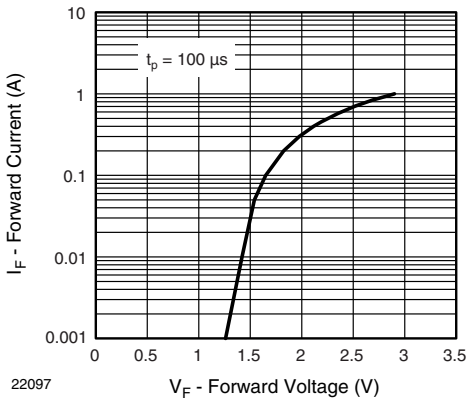


Fig. 2 - Forward Current Limit vs. Ambient Temperature

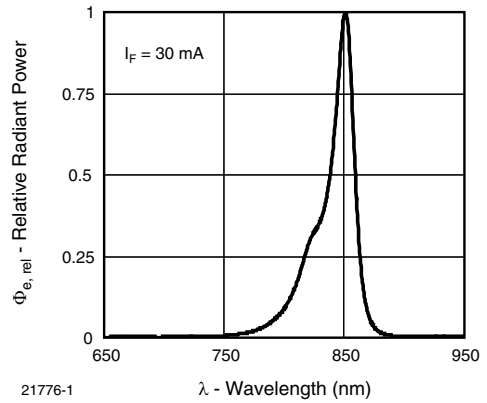
BASIC CHARACTERISTICS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$V_F$		1.65	1.9	V
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$	$V_F$		2.9		V
Temperature coefficient of $V_F$	$I_F = 1\text{ mA}$	$TK_{V_F}$		-1.4		mV/K
	$I_F = 10\text{ mA}$	$TK_{V_F}$		-1.18		mV/K
Reverse current		$I_R$	not designed for reverse operation			$\mu\text{A}$
Junction capacitance	$V_R = 0\text{ V}, f = 1\text{ MHz}, E = 0\text{ mW/cm}^2$	$C_J$		125		pF
Radiant intensity	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$I_e$	5	10	15	mW/sr
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$	$I_e$		85		mW/sr
Radiant power	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$\phi_e$		50		mW
Temperature coefficient of radiant power	$I_F = 100\text{ mA}$	$TK_{\phi_e}$		-0.35		%/K
Angle of half intensity		$\varphi$		$\pm 60$		deg
Peak wavelength	$I_F = 100\text{ mA}$	$\lambda_p$	840	850	870	nm
Spectral bandwidth	$I_F = 30\text{ mA}$	$\Delta\lambda$		30		nm
Temperature coefficient of $\lambda_p$	$I_F = 30\text{ mA}$	$TK_{\lambda_p}$		0.25		nm
Rise time	$I_F = 100\text{ mA}, 20\% \text{ to } 80\%$	$t_r$		10		ns
Fall time	$I_F = 100\text{ mA}, 20\% \text{ to } 80\%$	$t_f$		10		ns
Virtual source diameter		$d$		0.5		mm

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)



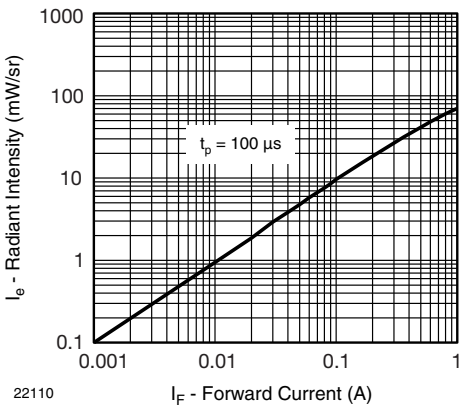
22097

Fig. 3 - Forward Current vs. Forward Voltage



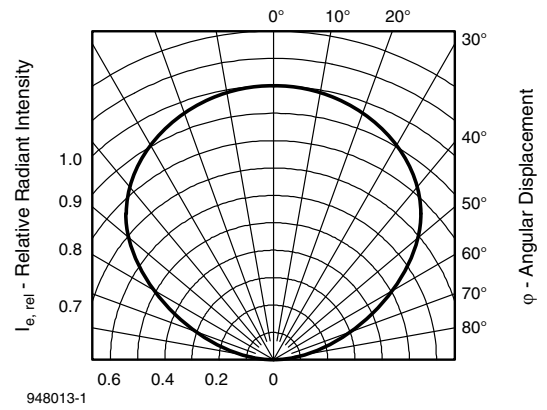
21776-1

Fig. 5 - Relative Radiant Power vs. Wavelength



22110

Fig. 4 - Radiant Intensity vs. Forward Current



948013-1

Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

**REFLOW SOLDER PROFILE**

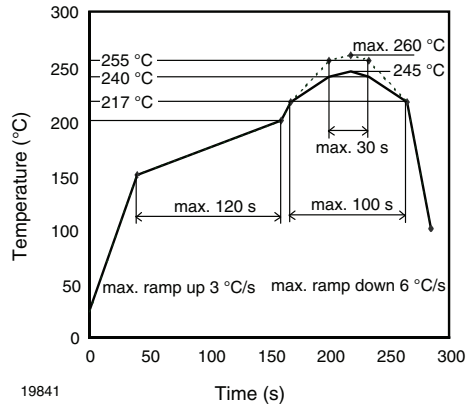


Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

**DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

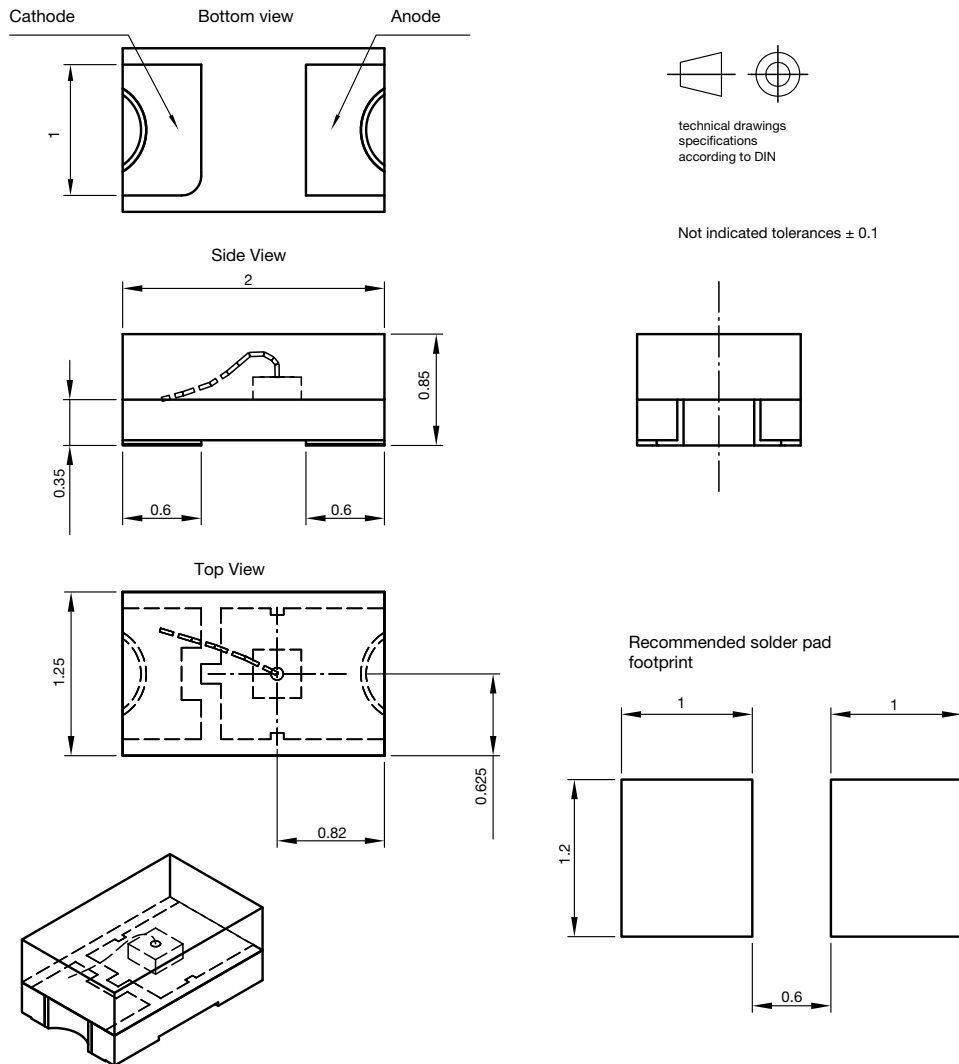
**FLOOR LIFE**

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:  
 Moisture sensitivity: level 3  
 Floor life: 168 h  
 Conditions:  $T_{amb} < 30\text{ }^{\circ}\text{C}$ ,  $RH < 60\%$

**DRYING**

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label.  
 Devices taped on reel dry using recommended conditions 192 h at  $40\text{ }^{\circ}\text{C}$  (+  $5\text{ }^{\circ}\text{C}$ ),  $RH < 5\%$ .

**PACKAGE DIMENSIONS** in millimeters



Drawing-No.: 6.541-5083.01-4  
 Issue: 2; 10.09.2013

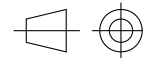


**BLISTER TAPE DIMENSIONS** in millimeters



Not indicated tolerances ±0.1

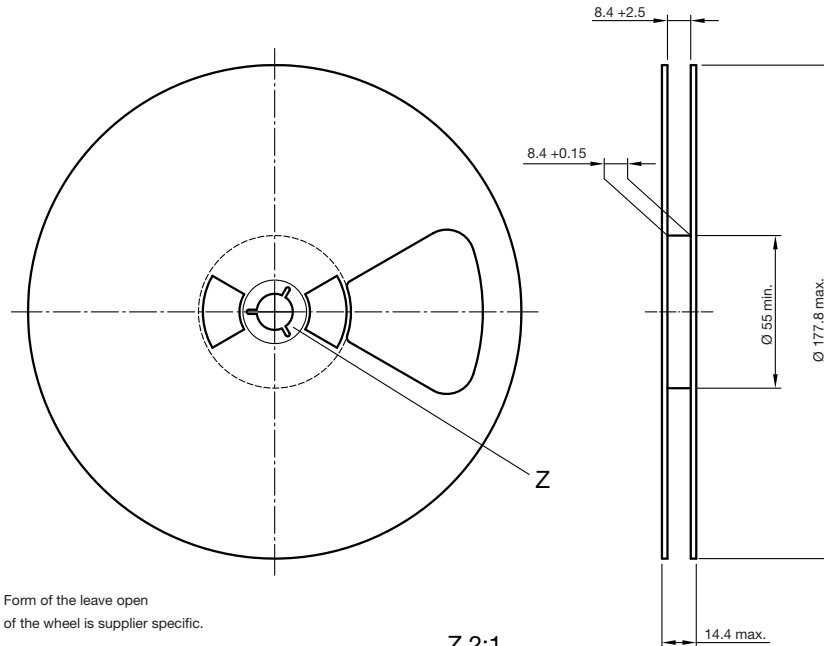
Reel off direction →



technical drawings according to DIN specifications

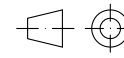
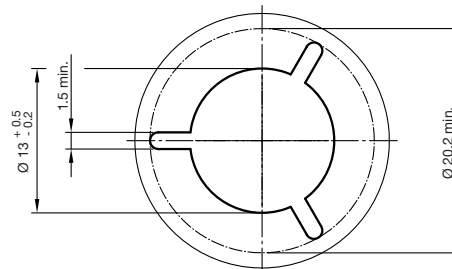
Drawing-No.: 9.700-5352.01-4  
Issue: 1; 13.04.10  
22112

**REEL DIMENSIONS** in millimeters



Form of the leave open of the wheel is supplier specific.

Z 2:1



technical drawings according to DIN specifications

Drawing-No.: 9.800-5096.01-4  
Issue: 2; 26.04.10  
20875



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